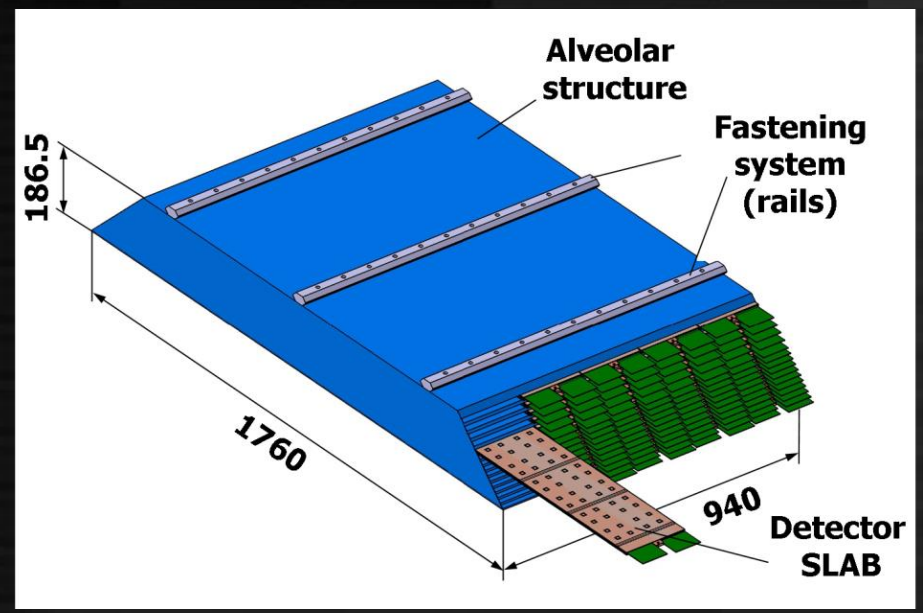
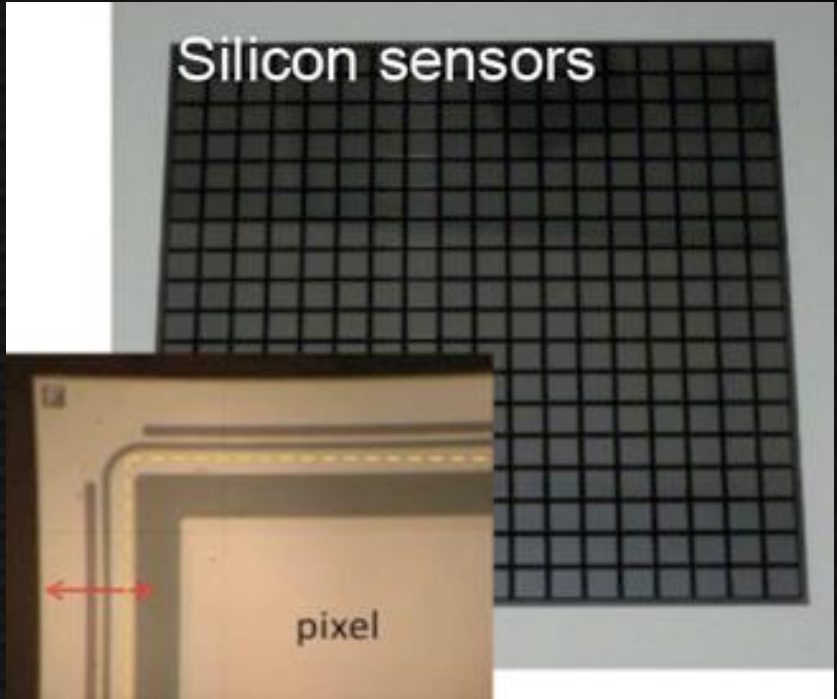
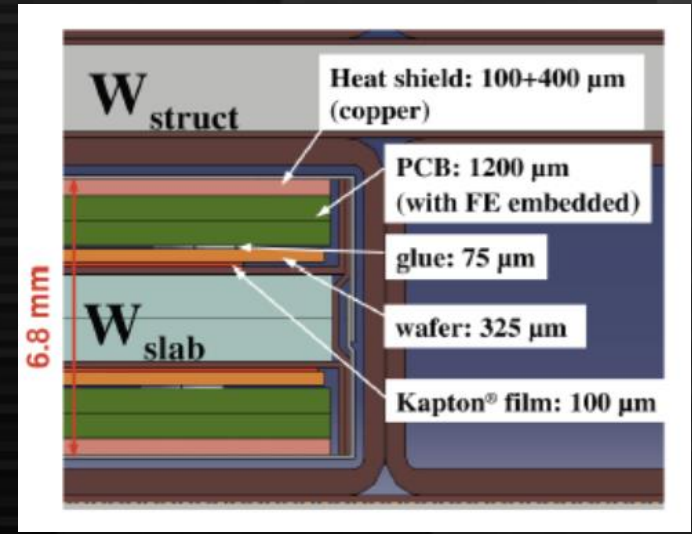
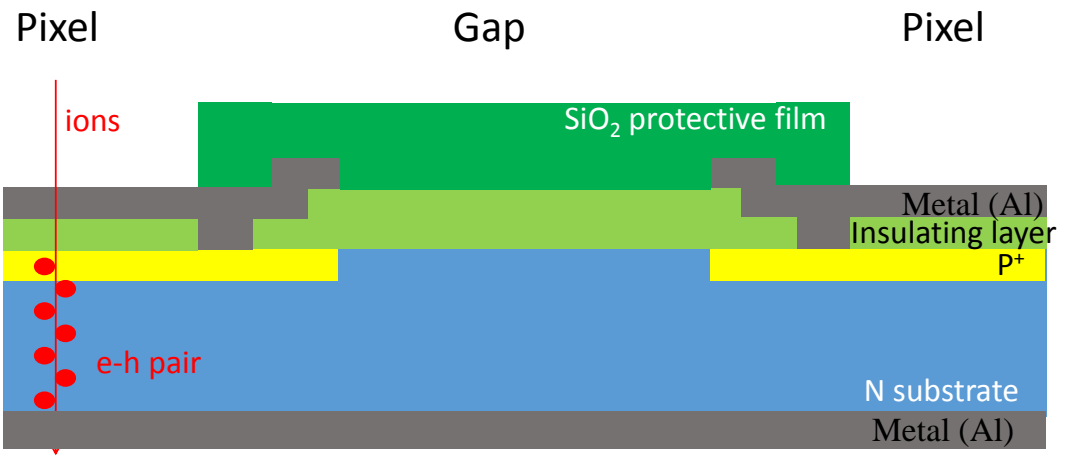




# Status of the CALICE SiW ECAL

Taikan Suehara  
(Kyushu University, Japan)

# SiW-ECAL: design



# Progress in SiW-ECAL

## Electronics & test beam

- FEB11 production
- Test beam plan
- Chip-in-board progress
- SKIROC test board for BGA
- Baby sensor readout

## Sensor design

- Resistivity
- Thickness
- Guard-ring, cutting edge
- Hexagonal sensor
- Radiation test
- New idea

## Non-ILC activities

- CMS endcap calorimeter
- ATLAS preshower

# Progress in SiW-ECAL

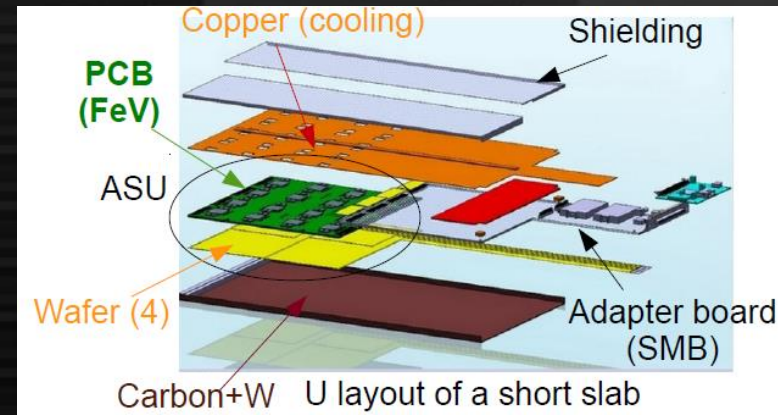
## Electronics & test beam

- FEB11 production
- Test beam plan
- Chip-in-board progress
- SKIROC test board for BGA
- Baby sensor readout

# FEB11

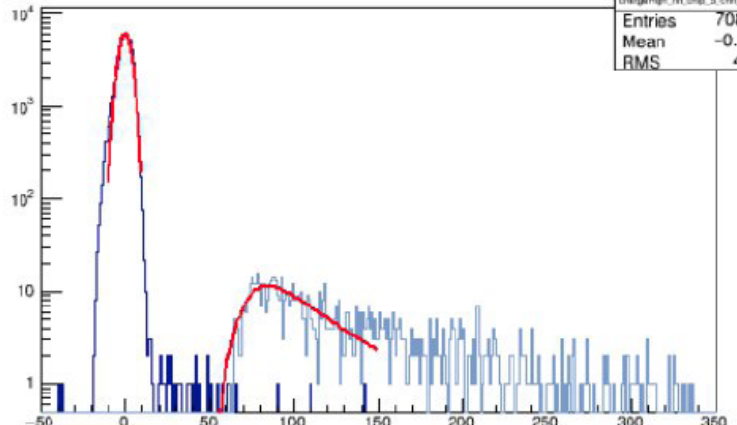
## FEB11 features

- One board / four wafers, 16 ASICs
- Long slab tested on 4 FEB daisy-chained
- Fixed the problem on afterpulsing
- Fully compatible with power-pulsing

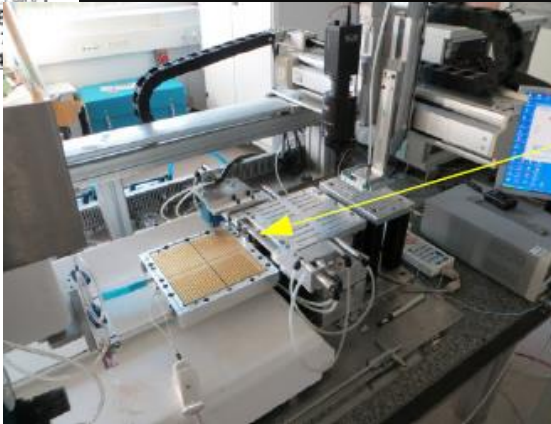


*Example of Cosmics for 1st glued ASU, Not et assembled (not fully shielded)*

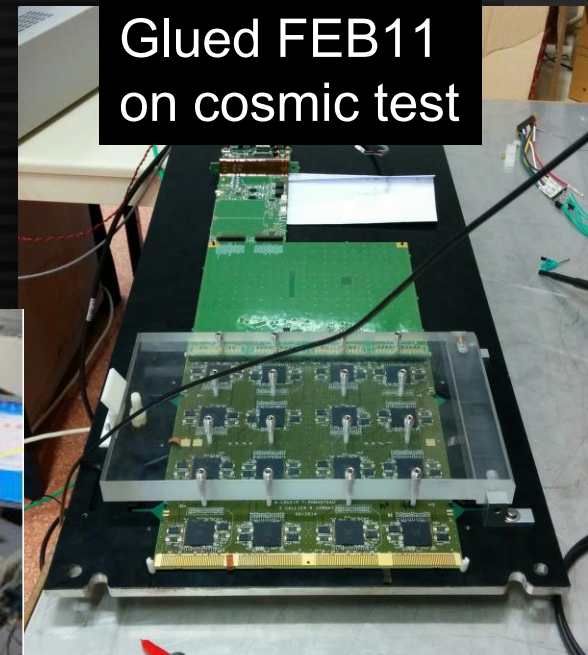
chargeHigh, Filtred Chip 5 channel 7 column 0



Gluing machine used for FEB11



Glued FEB11 on cosmic test



# Test beam plan

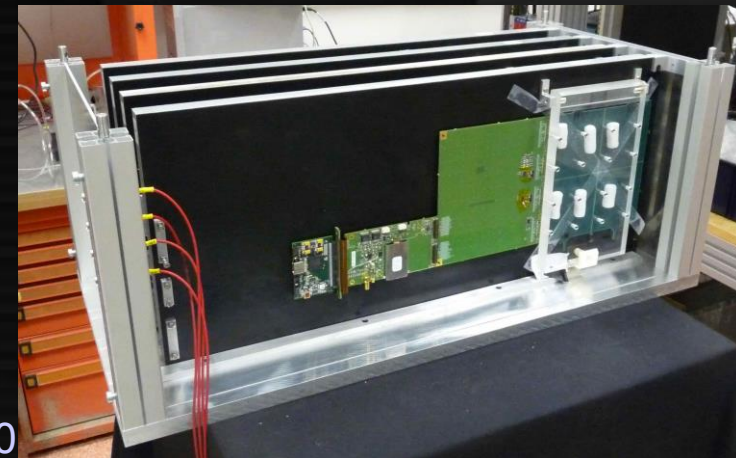
**SPS: November 2015**

CERN

schedule issue date: 01-Sep-2015      Version: 2.5.4

	Mon 2 Nov	Tue 3 Nov	Wed 4 Nov	Thu 5 Nov	Fri 6 Nov	Sat 7 Nov	Sun 8 Nov	Mon 9 Nov	Tue 10 Nov	Wed 11 Nov	Thu 12 Nov	Fri 13 Nov	Sat 14 Nov	Sun 15 Nov	Mon 16 Nov	Tue 17 Nov	Wed 18 Nov	Thu 19 Nov	Fri 20 Nov	Sat 21 Nov	Sun 22 Nov	Mon 23 Nov	Tue 24 Nov	Wed 25 Nov	Thu 26 Nov	Fri 27 Nov	Sat 28 Nov	Sun 29 Nov	Mon 30 Nov	Tue 1 Dec	Wed 2 Dec	Thu 3 Dec	Fri 4 Dec	Sat 5 Dec	Sun 6 Dec
Week	45							46							47							48							49						
Machine	UA9															Caldex		setup														UA9			
T2 - H2	NA61 SHINE		D. Lazic RPE172													CMS ECAL							A. Aduszkiewicz PE152							NA61 SHINE					
T2 - H4	RD51 (+GIF)		G. Mallot													NA58 ECAL							HERD		NUCLEON							RE21 CBM			
			H. Dong															L. Tkachev							D. Emschermann										

- SPS north area, H2 beamline, “CMS ECAL”
- Nov. 4 – 16, ~20 participants support from AIDA2020 TNA
- Four FEB11 slabs + babies  
FEB with temporary setup  
babies include 0/1/2 GR



# (prelim) Physics program

Physics commissioning:

- Check proper running with high intensity  $\mu$ 's (X-check of cosmics)
- Thr. adjustment vs noise environment. (Maybe require shielding).

EM-Core Set-up: All slabs after  $5 X_0$  of W  $\rightarrow$  Strong correlation between SLAB's

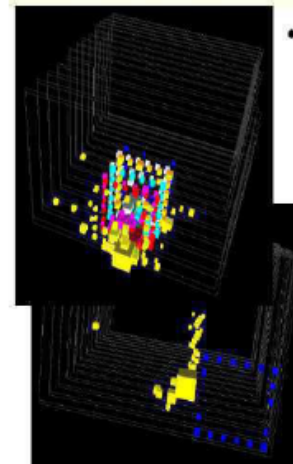
- Response at the core of a EM shower:
  - Explore the full dynamic range (1–2500 mip) using shower profile (for all mem depth).
    - e- runs of all energies, beam rates  $\rightarrow$  linearity
  - Check the responses at the wafers edges with  $\neq$  types of wafers (square events)
    - Scan in positions

HAD-Core set-up: same as EM-core or with  $1\lambda$  of W / SS

- Response to HE hadrons: look for SEU

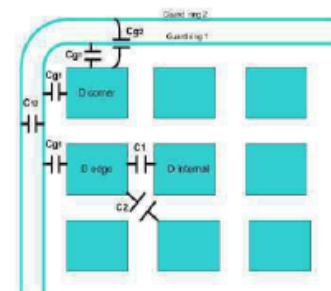
Mini-ECAL set-up: Sampling with  $3-4 \times 2.5 X_0$  and  $2-3 \times 5 X_0$

- Study of theoretical resolution & simulation tuning.
  - Scan in energy, position (and angle).



• "Square events"

- cross talk between guard rings and pixels

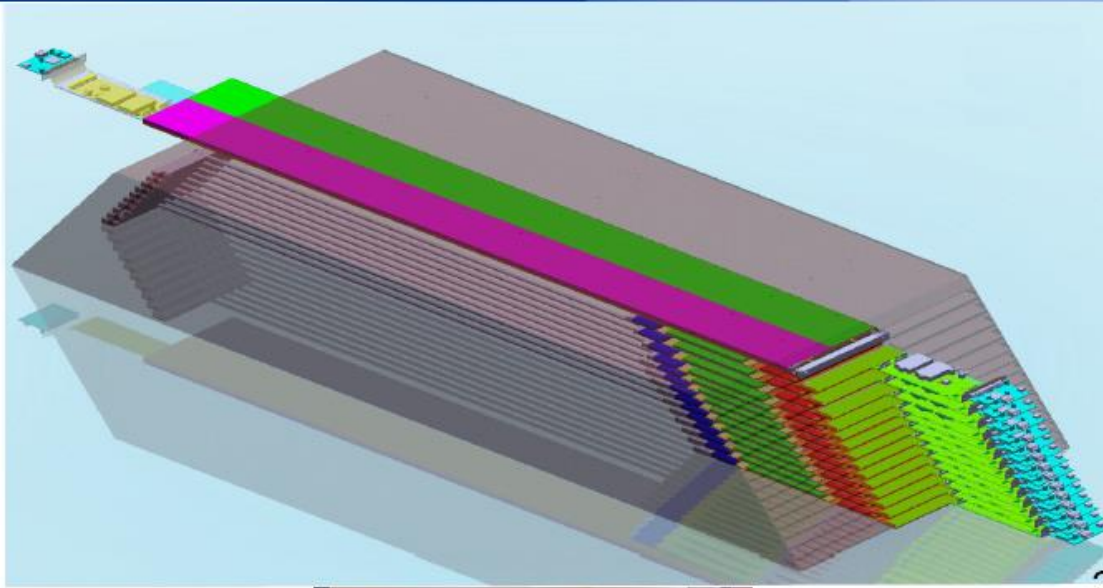


# SPS H2 beamline





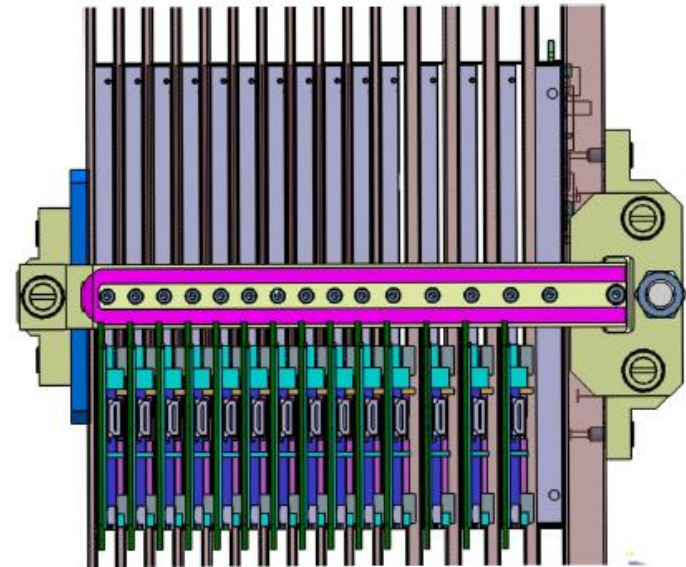
# “Final” prototype test (2016+)



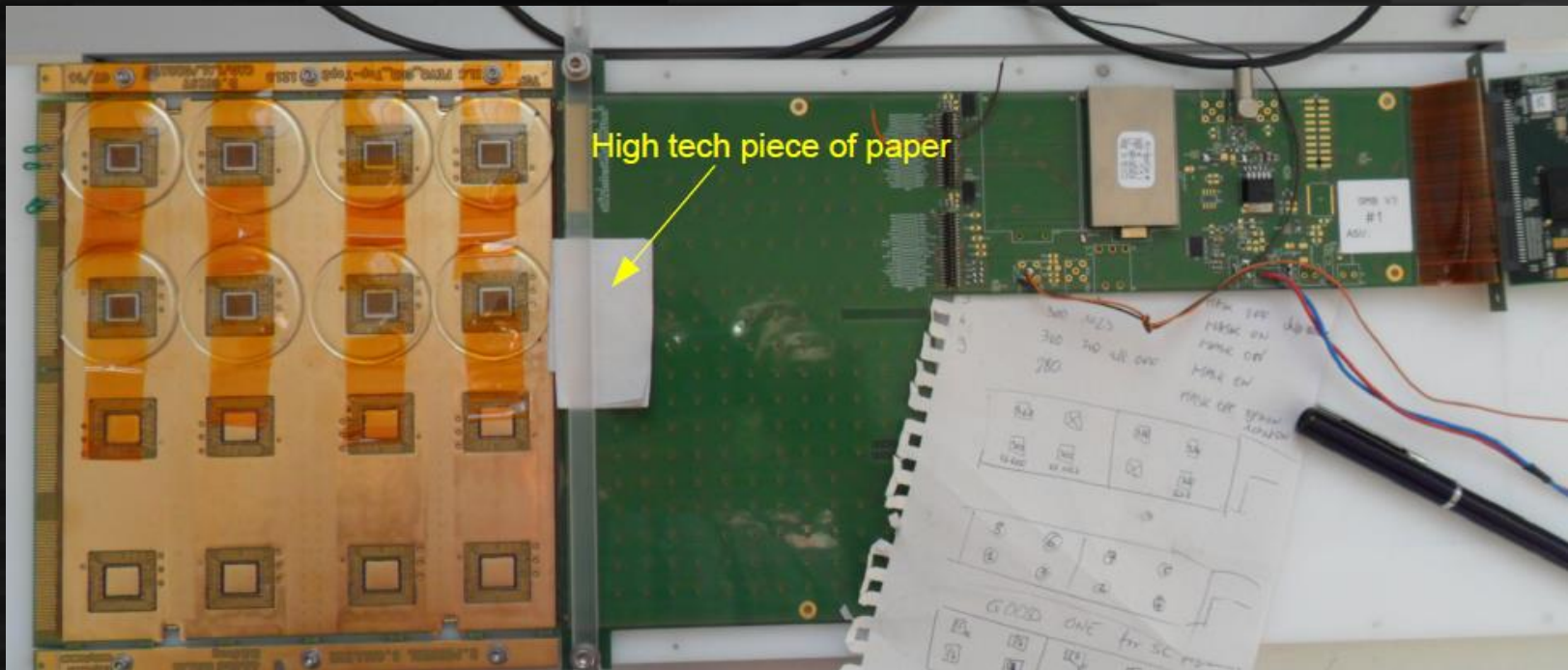
Tower of  $18 \times 18 \text{ cm}^2$  (2x2 wafers)  
14 Short SLABs  
1 Long SLAB

$2 \times 2.1 \text{ mm/lay}$

$2 \times 4.2 \text{ mm/lay}$

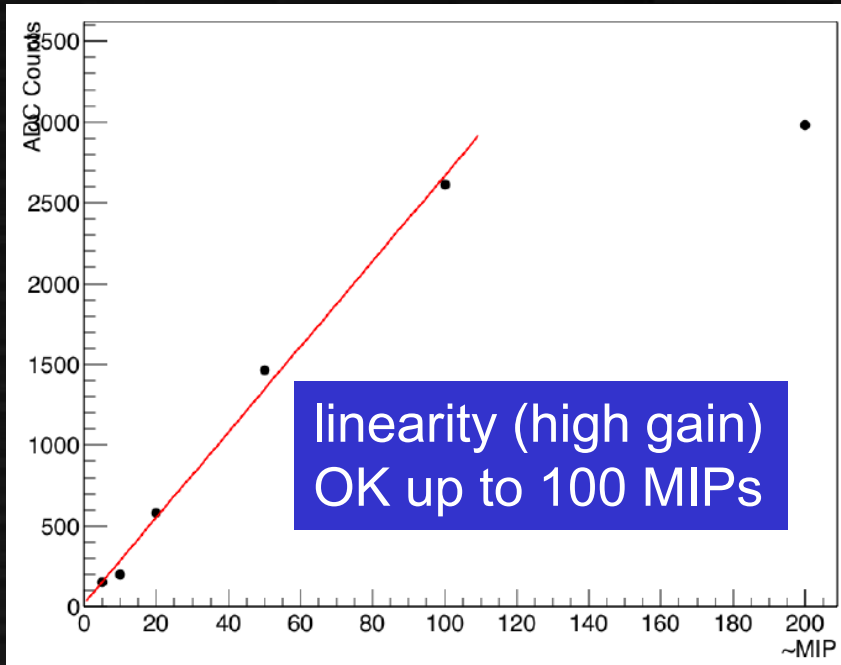


# Chip-in-Board progress

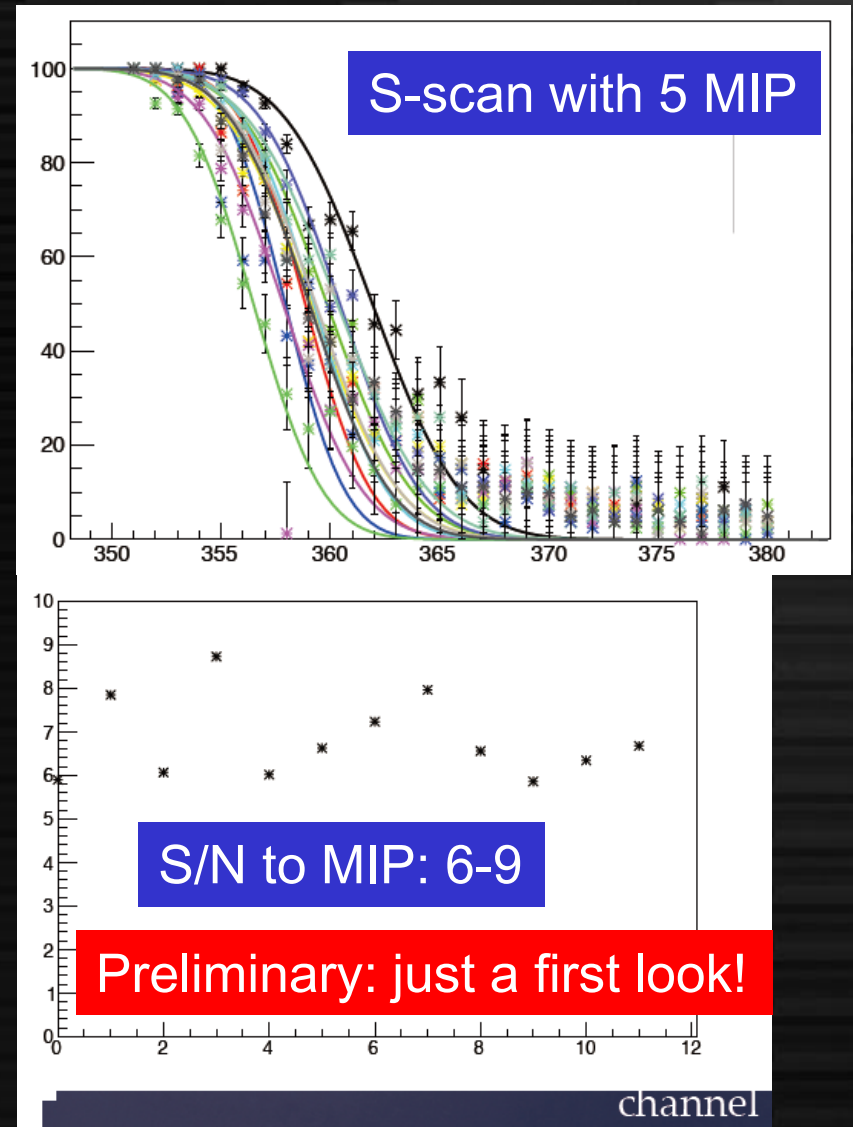


- PCB made in Korea, SKIROC wire-boded at CERN
- FEB8-based
- Optical shield (black plastic bag) needed
- Basic characteristics test done

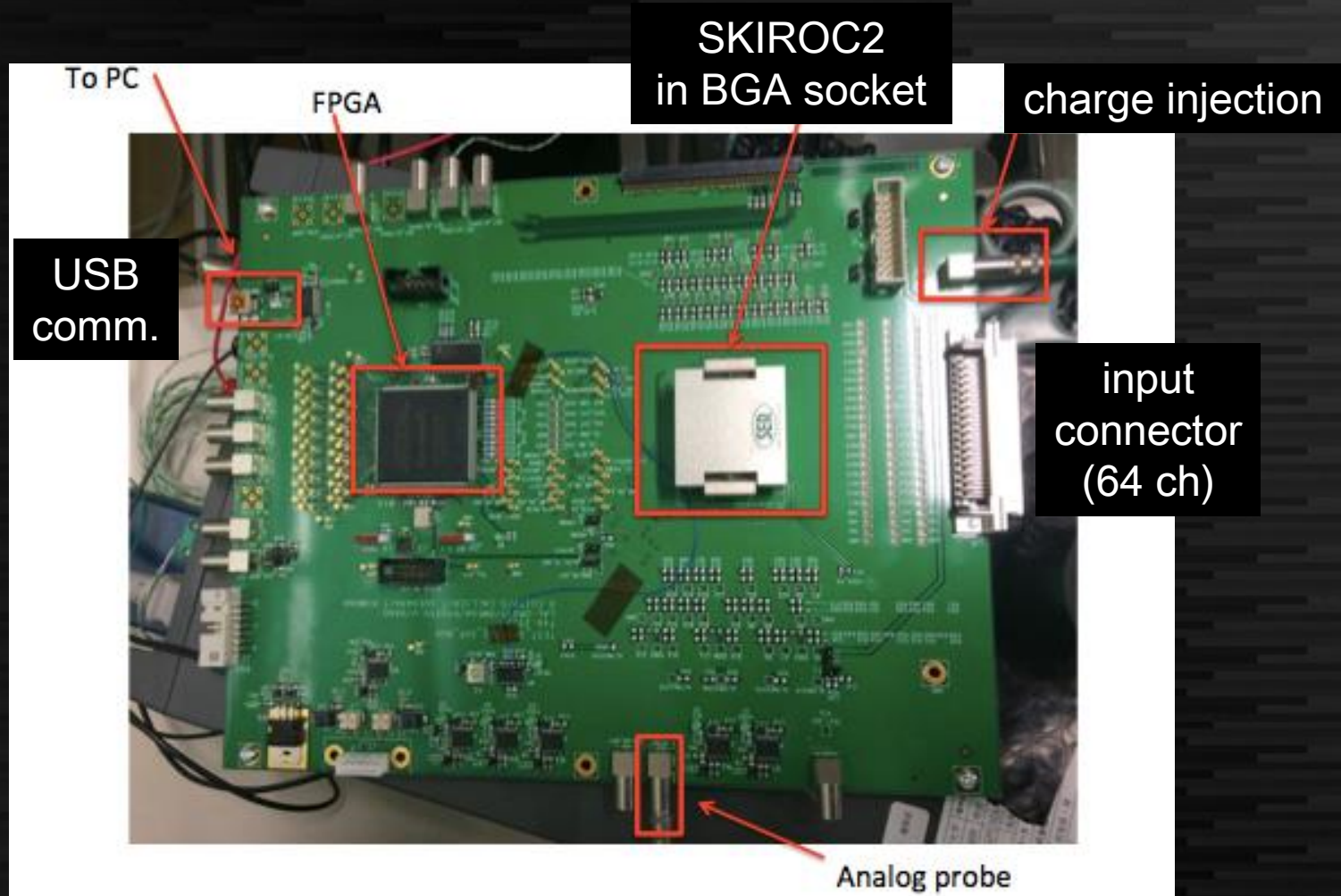
# CIB – measurement results



- Relatively in good shape (at least working)
- Noise reduction needed (better grounding etc.)

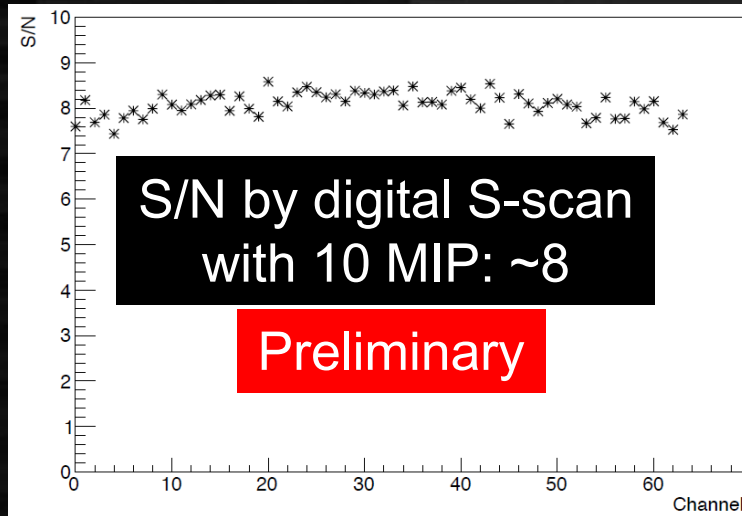
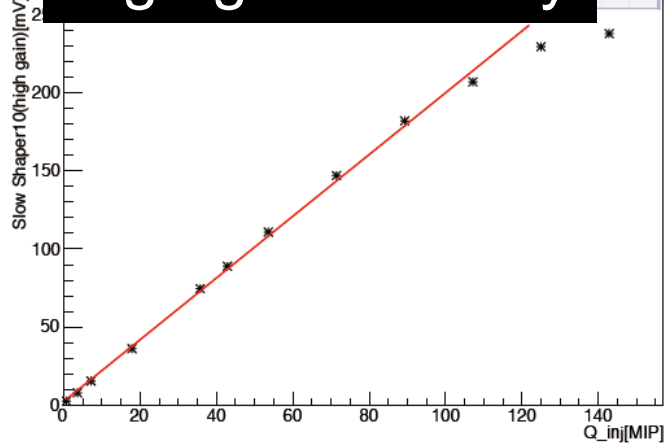


# SKIROC test board for BGA

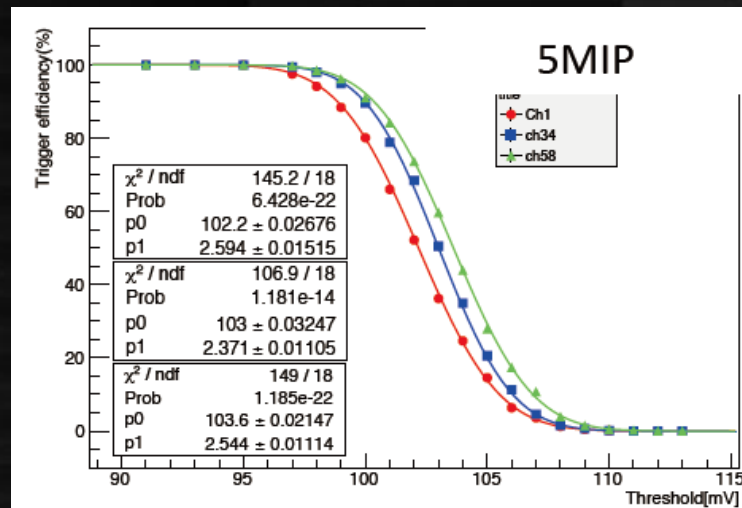
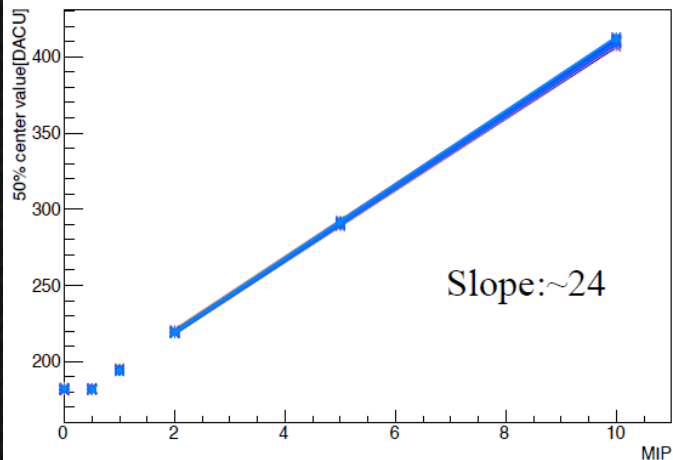


# Test board results

## High gain linearity



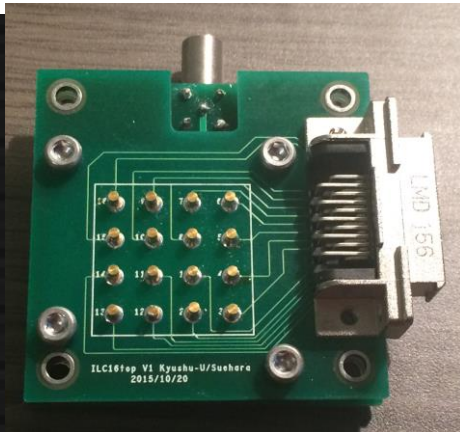
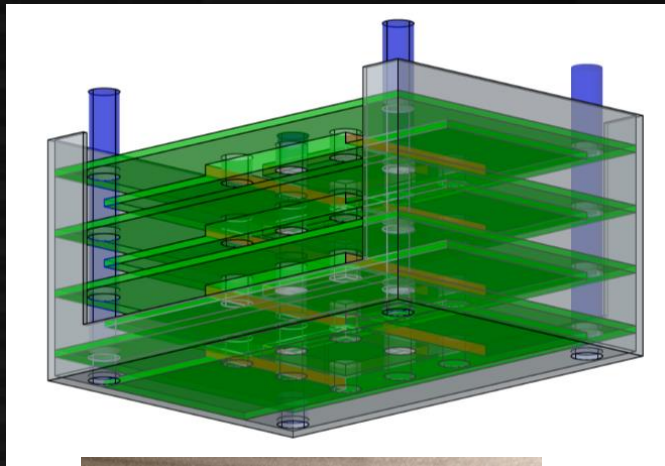
## Fast shaper linearity(0-64ch)



Analog S/N: consistent in several ch

# Baby sensor readout at testbeam

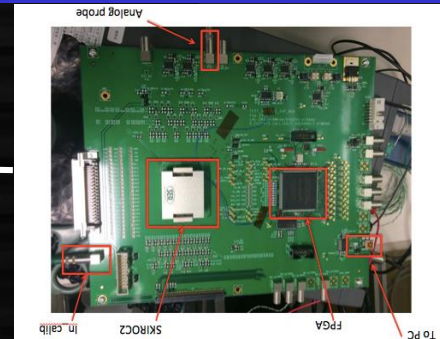
Sensor box  
(4 x baby(4x4/3x3))



PCB assembly with pins  
Silicon inside two PCBs

CALICOES-compatible  
raw data format

test board input (64 ch)



USB readout  
(C++,  
not LabView)

PC

slow clock

Adapter board

Ethernet  
(acq\_stop)

HDMI

CCC

- Shower extension (with FEB)
- Guard ring effects (0/1/2)

# Progress in SiW-ECAL

## Non-ILC activities

- CMS endcap calorimeter
- ATLAS preshower

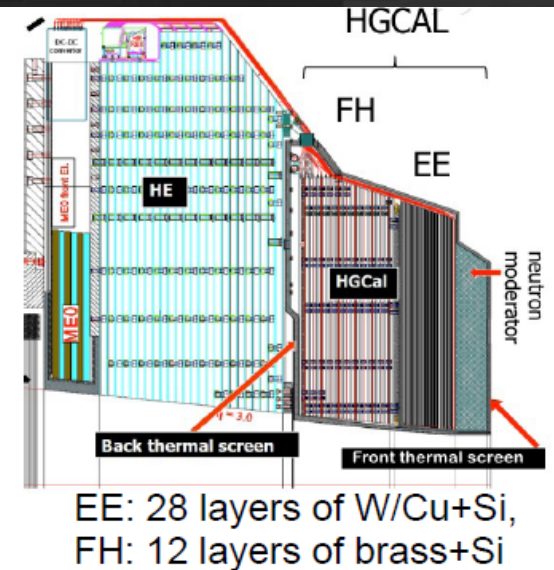
# Non-ILC activities



**CMS High Granularity CALorimeter: phase-2 upgrade of ECAL+HCAL endcaps for High Luminosity LHC**  
( $\geq 140$  pile up evs, up to  $10^{16}$  n/cm<sup>2</sup>)

Approved this spring, similar Si active detectors, inspired by ILC SiECAL, good synergy between two projects.

Common CERN beam tests planned (spring 2016), common front-end chips production (end 2015) (SKIROC for HGCal: much faster, no power pulsing).



Sep 2015: expression of interest for ATLAS:

High Granularity Timing Detector, Si timing preshower between LAr barrel and end-cap cryostats in  $2.5 < \eta < 4$  (4 layers in  $\Delta z = 6$  cm,  $\delta t \sim 50$  psec), also inspired by CALICE SiW ECAL.





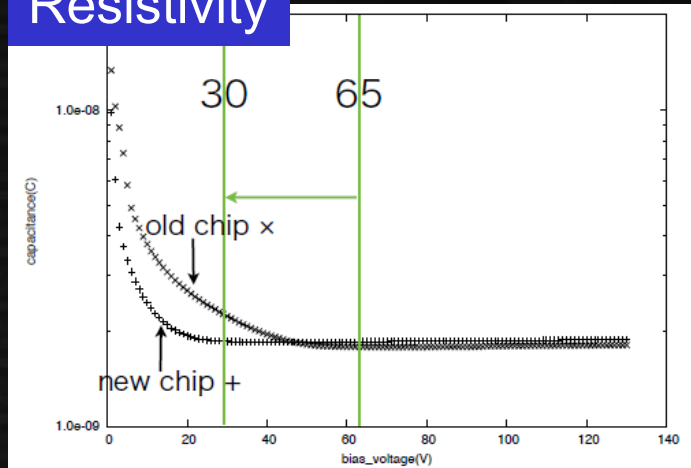
# Progress in SiW-ECAL

## Sensor design

- Resistivity
- Thickness
- Guard-ring, cutting edge
- Hexagonal sensor
- Radiation test
- New idea

# Parameters of sensors

## Resistivity



Hamamatsu changed to higher resistivity  
→ lower full-depletion V

## Thickness

320  $\mu\text{m}$  vs 500  $\mu\text{m}$   
Costs same  
More signal strength in 500  
More full-dep. voltage in 500  
**500  $\mu\text{m}$  sample arrived**

## Guard-rings & cut sizes

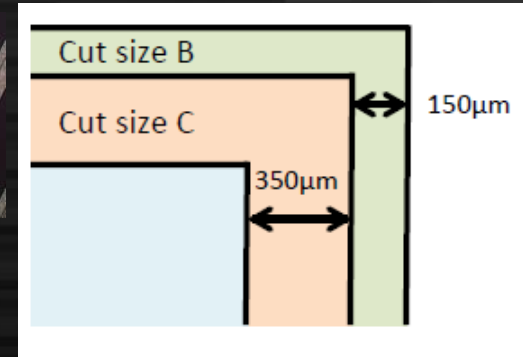


0GR, 1GR & split 2GR

1GR has **ring event**

→ trying 0GR

Currently no critical disadvantages found

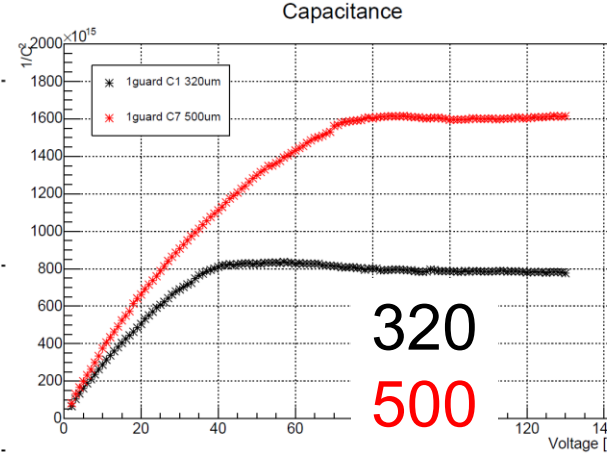
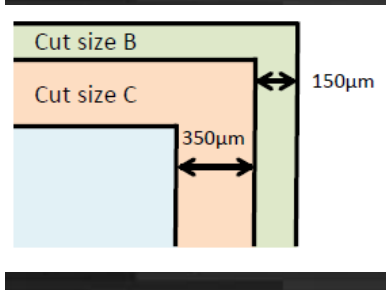
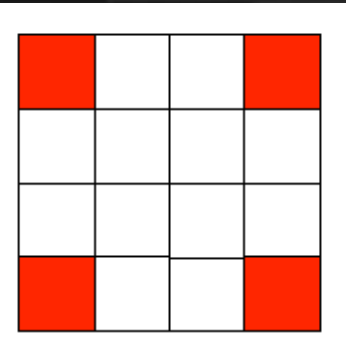
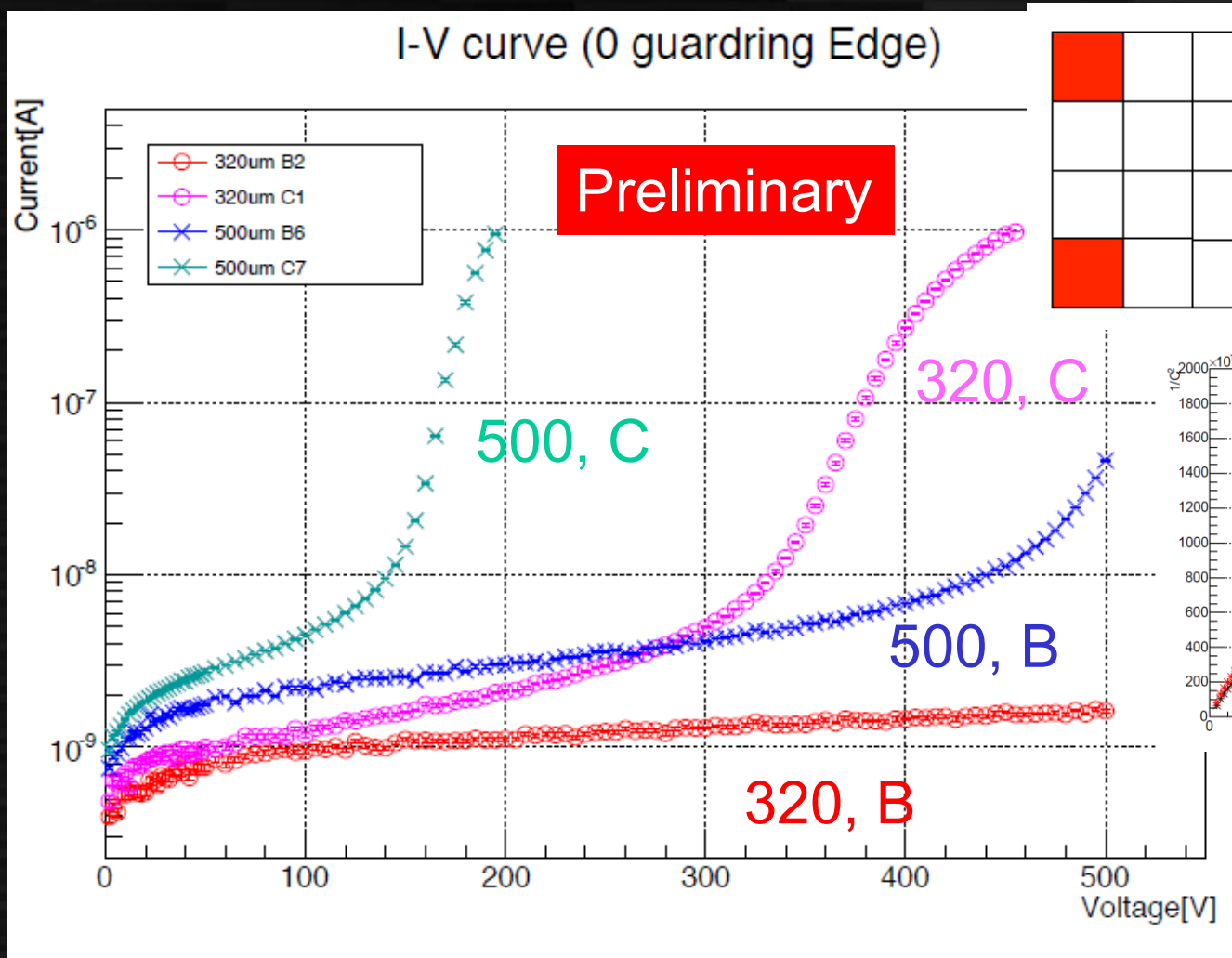


Cut sizes affect the breakdown voltage and leakage current

## Wafer size and manufacturer

Silicon industry is moving to 8 inch (or even 12)  
Hamamatsu recommends 6 inch in their fab.  
Consulting to another manufacturer (LFoundry)  
→ Sample not yet available

# A new results of 500 $\mu\text{m}$ sensor



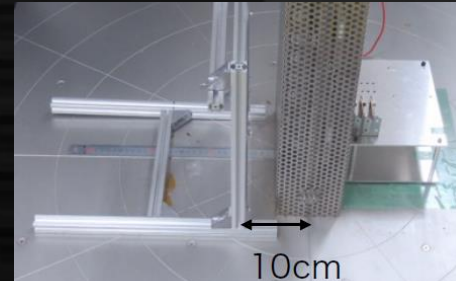
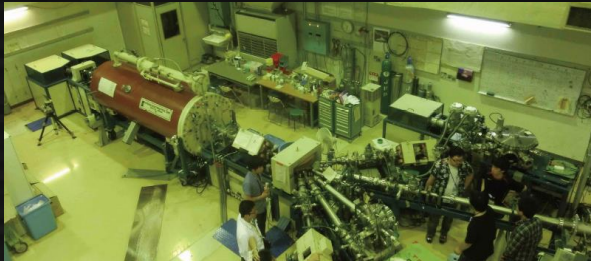
Full-dep. voltage  
~40V in 320  $\mu\text{m}$   
~80V in 500  $\mu\text{m}$

Cut size B is preferred esp. in 500  $\mu\text{m}$

# Irradiation test

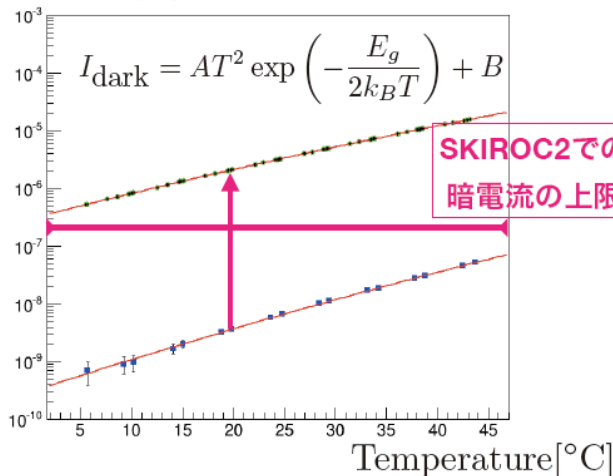
Neutron @ Kobe U, Jul-Aug 2015

Gamma @ Kyushu U, Oct 2015



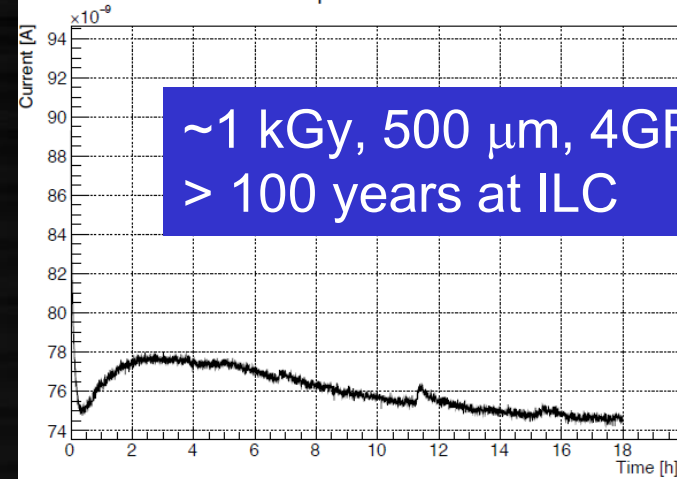
$^{60}\text{Co}$ ,  
~82 TBq

Dark Current [A]



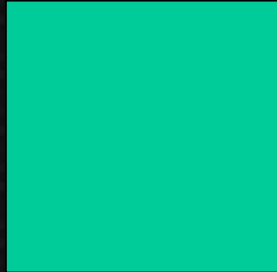
~1000 times more dark current on  
~ $7.5 \times 10^{11}$  neq/cm<sup>2</sup>  
acceptable in ~ $10^{10}$  neutrons  
capacitor & glue OK on  $10^{12}$

Time dependence at 120 V

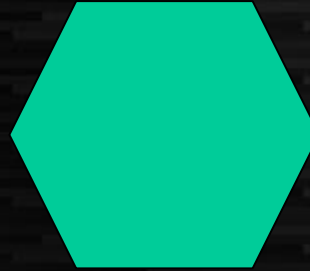


Without bias during irradiation  
~5 times larger current seen  
Crosstalk should be checked  
Continue irradiation on 0/1/2 GR

# Hexagonal sensors

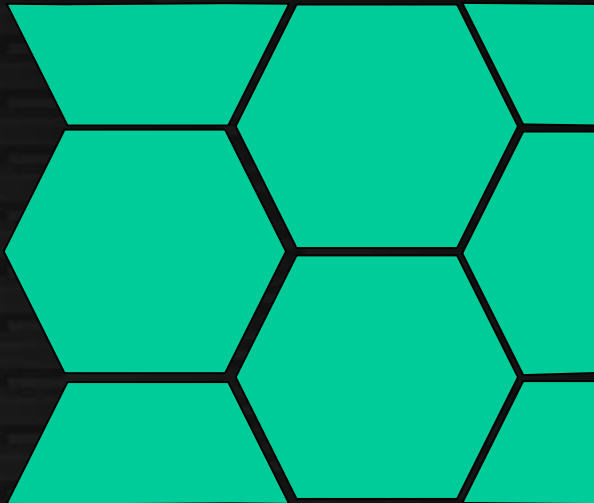


Square  
Max. 9.8x9.8 cm<sup>2</sup>  
Area = 96.04 cm<sup>2</sup>

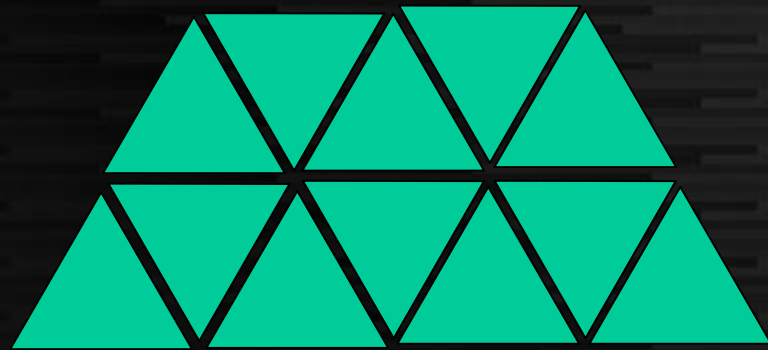


Hexagon  
Max. 6.9 cm each edge  
Area = 123.69 cm<sup>2</sup>  
(28.8% larger than square)

28.8% more area per wafer → 22.4% less wafers needed



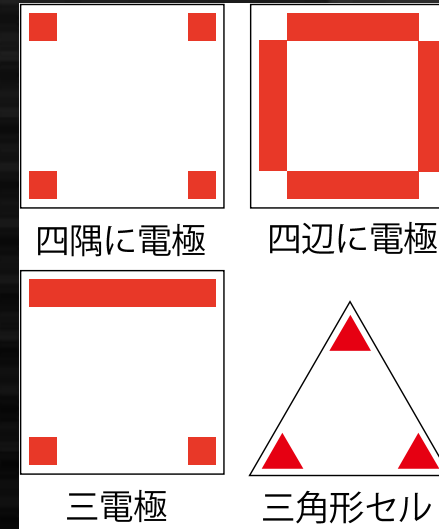
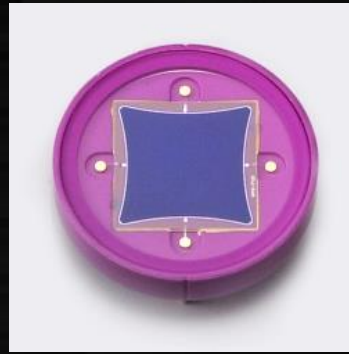
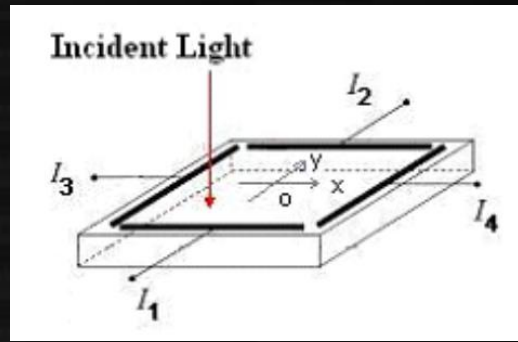
Preliminary idea  
of “Slab for hexagon”



Idea of “triangle pixels”  
for hexagonal sensors

Production of baby submitted:  
available in March 2016

# New idea – position sensitive det.



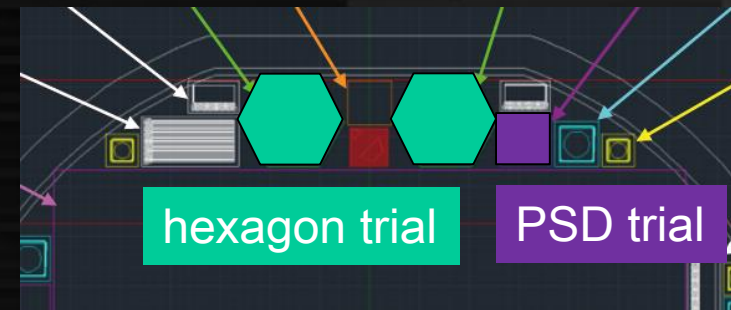
ideas on electrodes

Position sensitive detector (PSD)  
popular in laser measurement  
(produced by Hamamatsu)  
Application on heavy-ion exists

Divide signal into several electrodes  
→ less S/N expected

No much difference on electronics

For “precision shower start finder”  
to be used in inner layers of ECAL



Hexagons and PSD submitted  
along with other experiments  
~50 sensors on March 2016  
(~300 on 2016-2017)

# Summary

- Test beam on CERN SPS  
Nov. 4-16 for 4 FEB11 + baby
- CIB measurement started
- Application on CMS and ATLAS
- 500  $\mu\text{m}$  sensor tested
- Idea on hexagon and PSD